

REMARKS

This is in response to the Office Action dated February 9, 2006. Claims 1-10 and 19-22 are pending. This amendment after final should be entered because only dependent claims 2 and 5-6 have been amended to address the Section 112 and formality matters raised on page 2 of the Office Action; no new issues have been presented.

Section 112 & Formality Issues

Claim 2 stands objected to for allegedly lacking antecedent basis. The change to claim 2 herein addresses and overcomes any potential issue in this regard.

Claims 5-6 stand rejected under 35 U.S.C. Section 112, second paragraph. The changes to claims 5-6 herein address and overcome any potential issue in this regard. Claims 5-6 have been amended to clarify that a “non-contact through electrode” is one that is not electrically connected to an electrode pad of the semiconductor chip in which the non-contact through electrode is formed (it may ultimately be connected to another pad somewhere else in the device). For example and without limitation, Fig. 1 of the instant application illustrates non-contact through electrode 12(1); and insulating film 9 in Fig. 1 prevents the electrode 12(1) from being connected to a pad 2 in which the non-contact through electrode is formed. See also pg. 19, lines 12-16; and pg. 20, lines 8-14.

Claim 1 - Art Rejection

Claim 1 stands rejected under 35 U.S.C. Section 103(a) as being allegedly unpatentable over Tsunashima in view of Yu. Applicant notes that “Yu” appears to be 6,028,367 – not the 6,518,669 mentioned on page 3 of the Office Action. The Office Action contends that Tsunashima discloses all features of claim 1 except for “multiple through electrodes formed in a region within the electrode pads.” To account for this alleged deficiency in Tsunashima, the

Office Action cites to plugs 28 of Yu, and contends that plugs 28 are formed within metal pads 22, 26. This Section 103(a) rejection is respectfully traversed for at least the following reasons.

Claim 1 requires “chip-stack semiconductor device, comprising: multiple semiconductor chips vertically stacked on top of each other, wherein: each of the semiconductor chips includes electrode pads, and multiple through electrodes formed in a region within the electrode pads.”

The cited art fails to disclose or suggest the invention of claim 1 in this respect.

Tsunashima discloses pads 7. However, there are no through electrodes extending through pads 7 in Tsunashima. Thus, Tsunashima teaches directly away from the invention of claim 1 because the reference does not even use through-electrodes which extend through pads 7. Tsunashima does not disclose or suggest any through electrode extending through any pad 7, let alone multiple through electrodes extending through a given pad as required by claim 1. Citation to Yu cannot overcome the flaws of Tsunashima.

Because Tsunashima does not have any through electrodes extending through pads 7, there is no reason why one of ordinary skill in the art would have ever modified Tsunashima to have such through electrodes – there is simply no reason or suggestion in the art for doing so. In particular, there is nothing below pads 7 in Tsunashima that requires electrical connection. Furthermore, it can also be argued that there is nothing in Yu which suggests modifying Tsunashima in such a manner.

Furthermore, referring to Fig. 2 of Yu, it is clear that the plugs 28 are not formed “within” the metal pads 22, 26. Instead, plugs 28 in Yu are formed on (on top or below) the metal pads 22, 26 – not “within” pads as called for in claim 1. Yu from col. 5, line 69 to col. 6, line 9 indicates that a plurality of metal via plugs are deposited on top of the first metal pad 26, and that the second metal pad 24 is then also deposited on top of the via plugs 28, thereby

making clear that plugs 28 in Yu are formed on (on top or below) the metal pads 22, 26 – not “within” pads as called for in claim 1.

Thus, it will be appreciated that in Yu plugs 28 are not formed in a region “within” the electrode pads as required by claim 1. Thus, even the alleged combination (which applicant believes would be incorrect in any event) fails to meet the invention of claim 1.

Claim 20

Claim 20 requires that “a plurality of different through electrodes are provided in the first electrode pad, so that when viewed from above the plurality of through electrodes are located inside a periphery of the first electrode pad.” The cited art fails to disclose or suggest this feature either taken alone or in combination. It is clear that even the plugs 28 of Yu are not provided *in* a first electrode pad (instead, they are on top of pad 26). Thus, Thus, even the alleged combination (which applicant believes would be incorrect in any event) fails to meet the invention of claim 20.

Conclusion

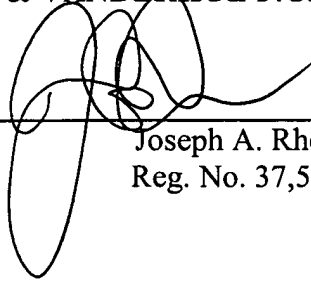
It is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

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Respectfully submitted,

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